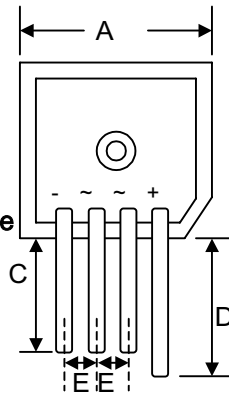


Features

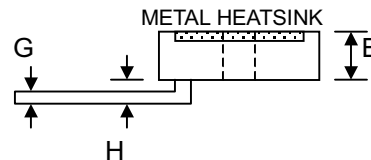
- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards
- Designed for Saving Mounting Space
- UL Recognized File # E223064
- Green Products in Compliance with the RoHS Directive



KBPC-S				
Dim	Min	Max	Min	Max
A	28.40	28.70	1.118	1.130
B	10.97	11.23	0.432	0.442
C	13.90	—	0.547	—
D	19.10	—	0.752	—
E	5.10	—	0.201	—
G	1.20 Ø TYPICAL		0.047 Ø TYPICAL	
H	3.05	3.60	0.120	0.142
			In mm In inch	

Mechanical Data

- Case: Epoxy Case with Heat Sink Internally Mounted in the Bridge Encapsulation
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 30 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



Maximum Ratings and Electrical Characteristics @_{T_A}=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristics	Symbol	-00S-G	-01S-G	-02S-G	-04S-G	-06S-G	-08S-G	-10S-G	Unit	
Peak Repetitive Reverse Voltage	V _{RRM}								V	
Working Peak Reverse Voltage	V _{RWM}	50	100	200	400	600	800	1000		
DC Blocking Voltage	V _R									
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	700	V	
Average Rectified Output Current @ _{T_C} = 55°C	I _O					15				A
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half-sine-wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}					300				A
						300				
						400				
Forward Voltage Drop (per element)	V _{FM}					1.1				V
Peak Reverse Current at Rated DC Blocking Voltage (per element)	I _R					5.0				µA
						500				
I ² t Rating for Fusing (t < 8.3ms) (Note 1)	I ² _t					374				A ² s
						374				
						664				
Typical Thermal Resistance (per element) (Note 2)	R _{θJC}					2.0				K/W
RMS Isolation Voltage from Case to Lead	V _{iso}					2500				V
Operating and Storage Temperature Range	T _j , T _{STG}					-65 to +150			°C	

Note: 1. Non-repetitive for t > 1ms and < 8.3ms.
2. Thermal resistance junction to case per element mounted on 220 x 220 x 50mm thick AL plate.

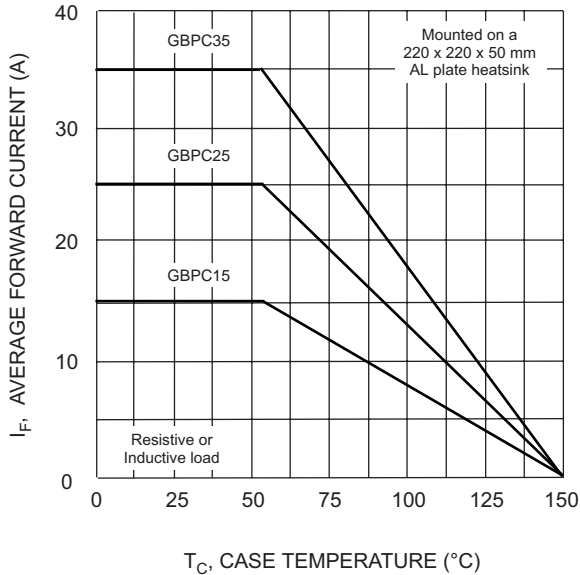


Fig. 1 Forward Current Derating Curve

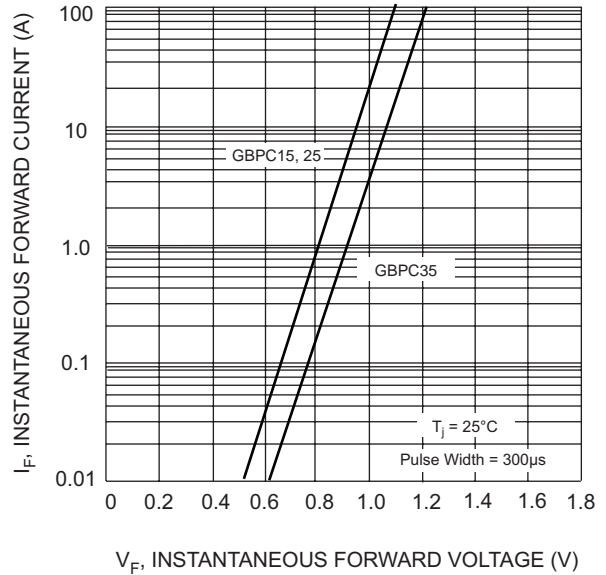


Fig. 2 Typical Forward Characteristics (per element)

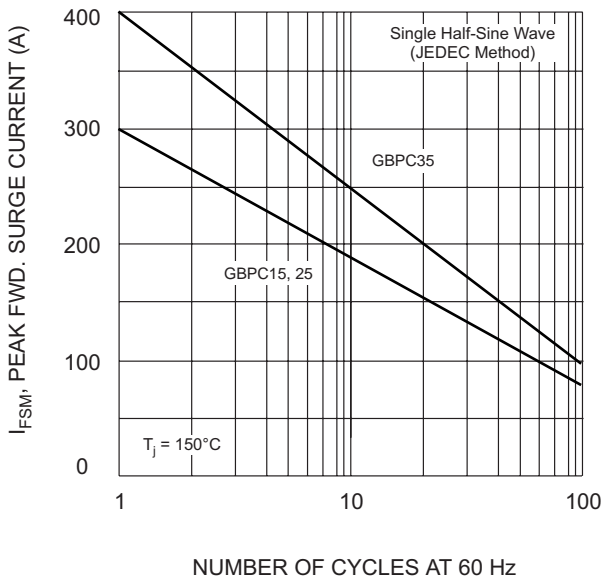


Fig. 3 Max Non-Repetitive Surge Current

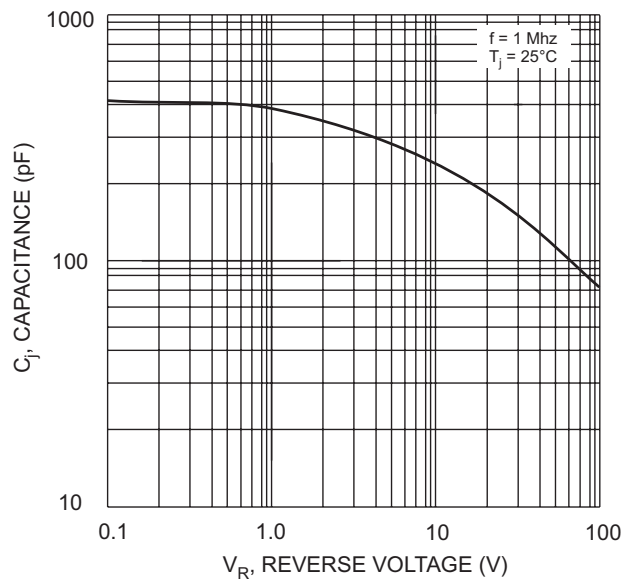


Fig. 4 Typical Junction Capacitance (per element)

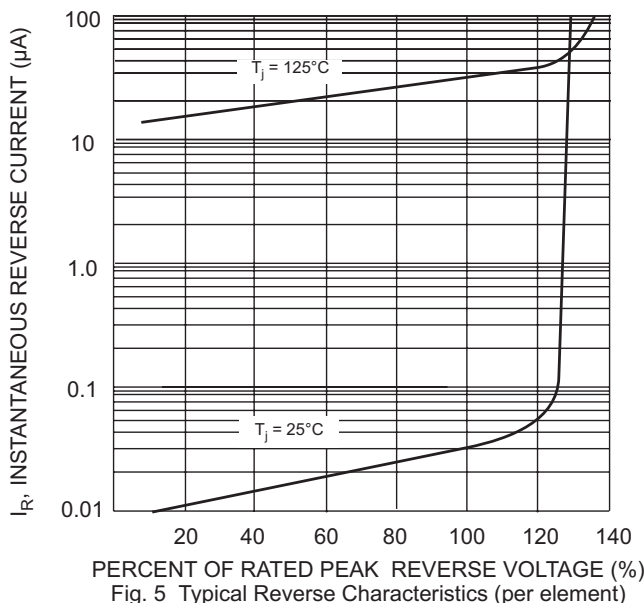


Fig. 5 Typical Reverse Characteristics (per element)

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